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(54) **METAL SENSE LINE CONTACT**

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ABSTRACT

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Methods, apparatuses, and systems related to a metal sense line contact are described. An example apparatus includes a sense line pillar comprising a barrier material over a semiconductor substrate. The sense line pillar further includes a liner material adjacent the barrier material. The sense line pillar further includes a first metal material over the barrier material. The sense line pillar further includes a second metal material over the first metal material. The sense line pillar further includes a cap material over the second metal material. The apparatus further cell contacts between a plurality of sense line pillars.

